

N-Channel 20V(D-S) MOSFET

Product summary		
V_{DS}	20	V
$R_{DS(ON)}$ (at $V_{GS}=4.5V$) Typ.	190	$m\Omega$
$R_{DS(ON)}$ (at $V_{GS}=2.5V$) Typ.	240	$m\Omega$
$I_D(T_A=25^\circ C)$	0.7	A

Features

- Low Threshold Voltage
- ESD protection up to 2 kV
- Small package DFN1006-3L

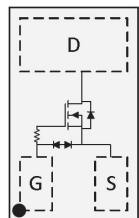
Applications

- Small Signal Switching
- Small Moto Driver

Pin Configuration



DFN1006-3L



Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECAD2004	DFN1006-3L	7"	10000pcs

Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 8	V
I_D	Continuous Drain Current ^{AC}	$T_A=25^\circ C$	A
		$T_A=70^\circ C$	A
I_{DM}	Pulse Drain Current Tested ^B	2.9	A
P_D	Power Dissipation ^{AC}	$T_A=25^\circ C$	W
T_J, T_{STG}	Junciton and Storage Temperature Range	-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JA}$	Thermal Resistance-Junction to ambient ^A	416	°C/W

Electrical Characteristics (at $T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	20	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 8\text{V}$	--	--	± 10	μA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.5	--	1.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^D	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=0.5\text{A}$	--	190	280	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=0.5\text{A}$	--	240	350	$\text{m}\Omega$
		$V_{\text{GS}}=1.8\text{V}, I_{\text{D}}=0.5\text{A}$	--	310	450	$\text{m}\Omega$
V_{SD}	Forward Voltage	$I_{\text{SD}}=0.5\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.3	V
Dynamic Parameters						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=10\text{V}$ $f=1\text{MHz}$	--	46	--	pF
C_{oss}	Output Capacitance		--	9.8	--	pF
C_{rss}	Reverse Transfer Capacitance		--	7.2	--	pF
Switching Parameters						
Q_g	Total Gate Charge	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=0.5\text{A}$ $V_{\text{GS}}=4.5\text{V}$	--	1.8	--	nC
Q_{gs}	Gate-Source Charge		--	0.15	--	nC
Q_{gd}	Gate-Drain Charge		--	0.25	--	nC
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=10\text{V}$ $I_{\text{D}}=0.5\text{A}$, $V_{\text{GS}}=4.5\text{V}, R_{\text{GEN}}=6\Omega$	--	34	--	ns
t_r	Turn-on Rise Time		--	97.3	--	ns
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	601	--	ns
t_f	Turn-off Fall Time		--	312	--	ns

A. Device mounted on FR-4 PCB, 1 inch x 1 inch x 0.062 inch.

B. Pulse width<380us, Single pulse

C. Maximum junction temperature $T_J=150^\circ\text{C}$.

D. Pulse test: Pulse width <380us duty cycle <2%.

Typical Characteristics

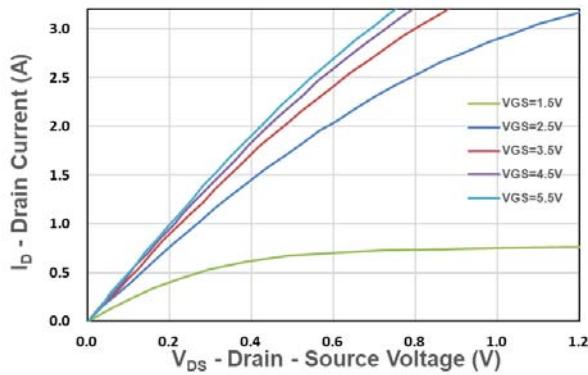


Figure 1. Output Characteristics

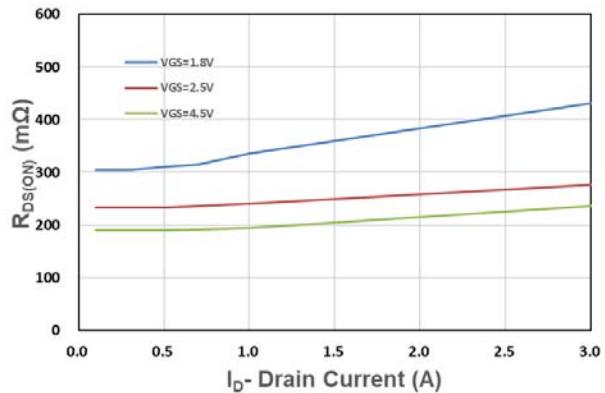


Figure 2. On-Resistance vs. I_D

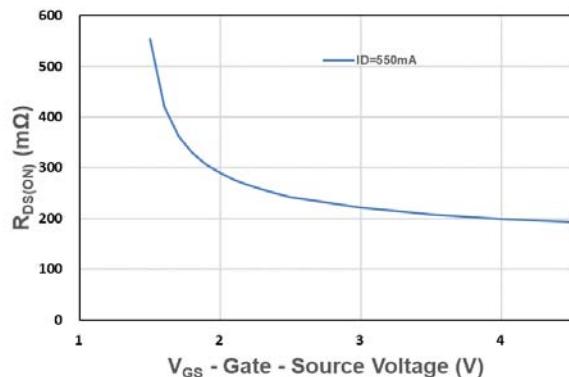


Figure 3. On-Resistance vs. V_{GS}

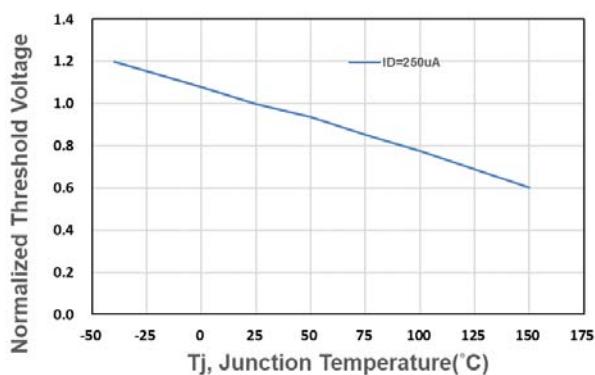


Figure 4. Gate Threshold Voltage

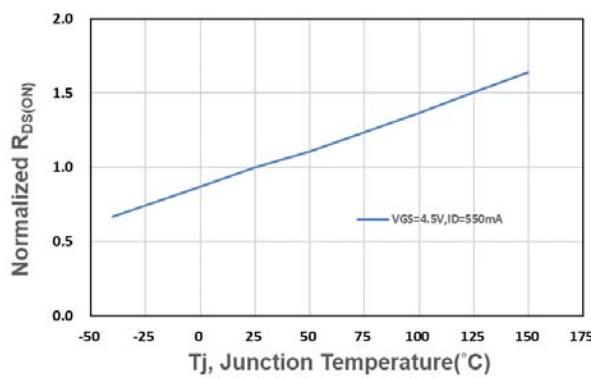


Figure 5. Drain-Source On Resistance

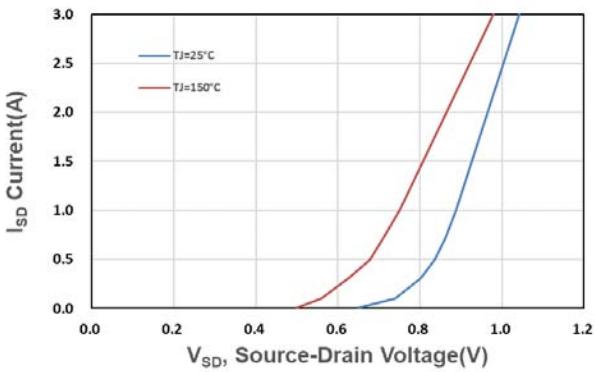


Figure 6. Source-Drain Diode Forward

Typical Characteristics

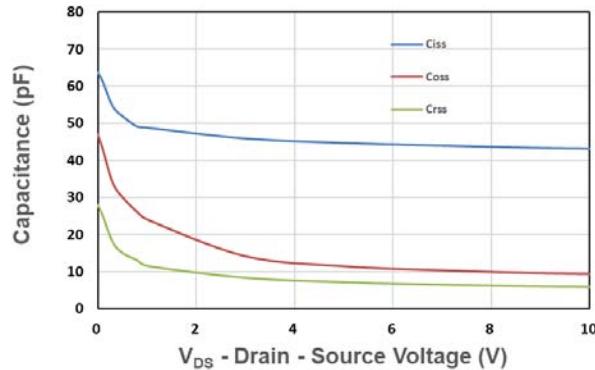


Figure 7. Capacitance

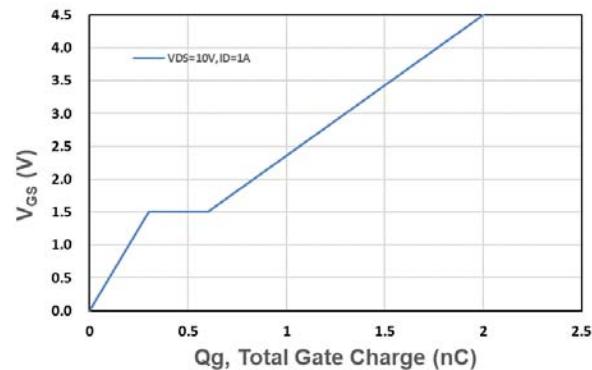


Figure 8. Gate Charge Characteristics

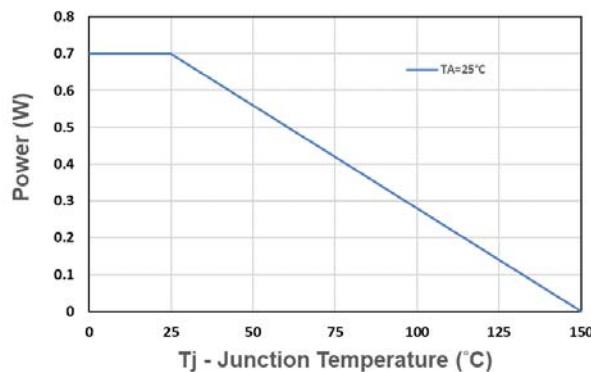


Figure 9. Power Dissipation

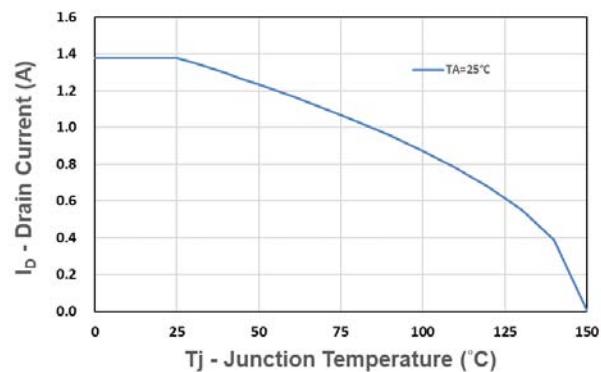


Figure 10. Drain Current

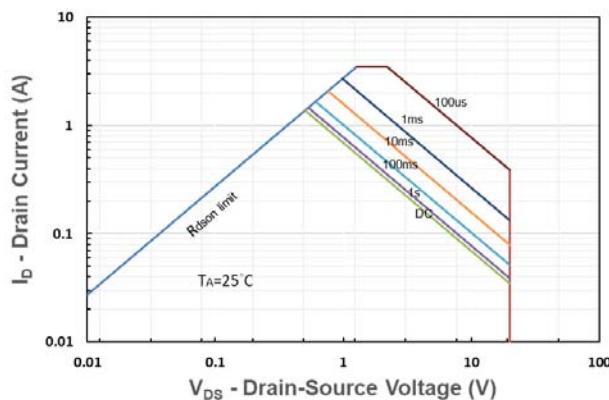


Figure 11. Safe Operating Area

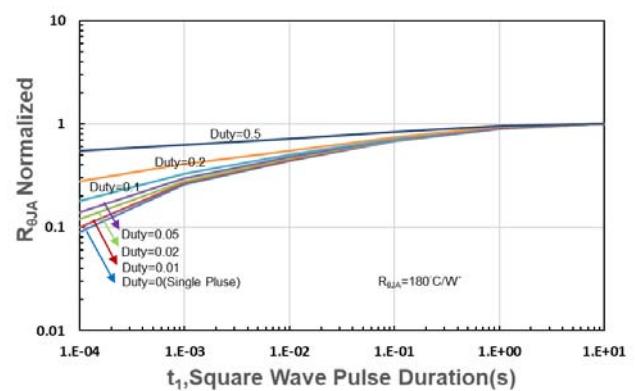
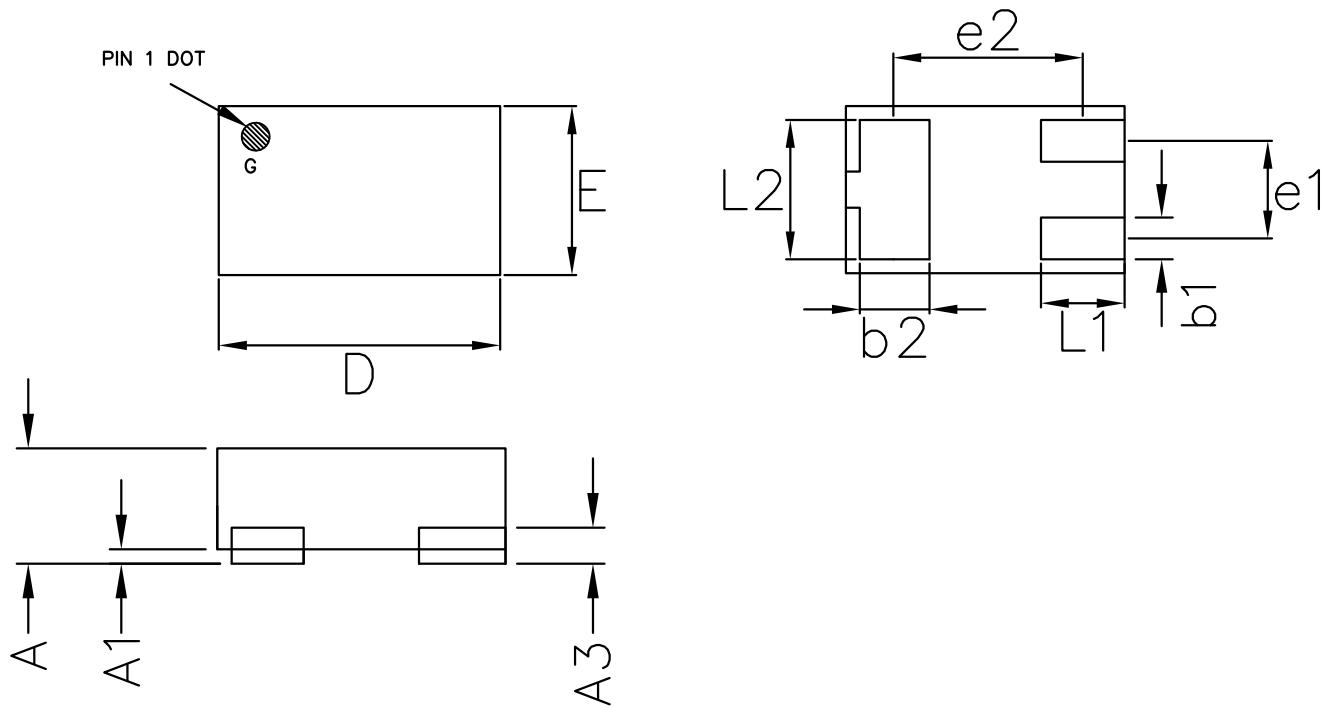


Figure 12. R_{θJA} Transient Thermal Impedance

DFN1006-3L Package Information


COMMON DIMENSIONS(MM)			
PKG.	X1: EXTREME THIN		
REF.	MIN.	NOM.	MAX
A	>0.40	—	0.55
A ¹	0.00	—	0.05
A ³	0.125 REF.		
D	0.95	1.00	1.05
E	0.55	0.60	0.65
b ₁	0.10	0.15	0.20
b ₂	0.20	0.25	0.30
L ₁	0.20	0.30	0.40
L ₂	0.40	0.50	0.60
e ₁	0.35 BSC		
e ₂	0.675 BSC		